



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
* : Required Field			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	01/09/2015
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
------------------------------	-------------	----------------------------	-----------------

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	ENYD*V692IL2	A	Z7GA	01/09/2015
Amount	UoM	Unit type	ST ECOPACK Grade	
5.500	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	2.6X1.8X0.5	16	No lead	
Comment	Package: VFQFPN16 2.6x1.8x0.5 PITCH 0.4; MD valid for LD1117S50TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ENYD*V692IL2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	0.157	mg	supplier	Silicon Die	Si	7440-21-3		0.136	mg	866242	24727
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	12739	364
Silicon Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	6369	182
Silicon Die				supplier	metallization	Tungsten (W)	7440-33-7		0.005	mg	31847	909
Silicon Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.001	mg	6369	182
Silicon Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.012	mg	76433	2182
Leadframe	Copper and its alloy	1.075	mg	supplier	Alloy	Cu	7440-50-8		1.042	mg	969302	189455
Leadframe				supplier	Alloy	Cr	7440-47-3		0.003	mg	2791	545
Leadframe				supplier	Alloy	Sn	7440-31-5		0.003	mg	2791	545
Leadframe				supplier	Alloy	Zn	7440-66-6		0.002	mg	1860	364
Leadframe				supplier	coating	Palladium	7440-05-3		0.001	mg	930	182
Leadframe				supplier	coating	Gold	7440-57-5		0.001	mg	930	182
Leadframe				supplier	coating	Nickel	7440-02-0		0.023	mg	21395	4182
Die Attach	Other organic materials	0.091	mg	supplier	Glue	Treated silica	14808-60-7		0.014	mg	153846	2545
Die Attach				supplier	Glue	Glycol ethers	34590-94-8		0.021	mg	230769	3818
Die Attach				supplier	Glue	Metal oxide	1344-28-1		0.011	mg	120879	2000
Die Attach				supplier	Glue	Curing agent & hardener	23996-25-0		0.007	mg	76923	1273
Die Attach				supplier	Glue	Epoxy resins	67924-34-9		0.038	mg	417582	6909
Bonding	Other inorganic materials	0.133	mg	supplier	Bonding wire	Gold	7440-57-5		0.133	mg	1000000	24182
Encapsulation	Other organic materials	4.044	mg	supplier	Molding Compound	Silica fused	60676-86-0		3.613	mg	893422	656909
Encapsulation				supplier	Molding Compound	Epoxy resin	Proprietary		0.213	mg	52671	38727
Encapsulation				supplier	Molding Compound	Phenol resin	Proprietary		0.213	mg	52671	38727
Encapsulation				supplier	Molding Compound	Carbon black	1333-86-4		0.005	mg	1236	909